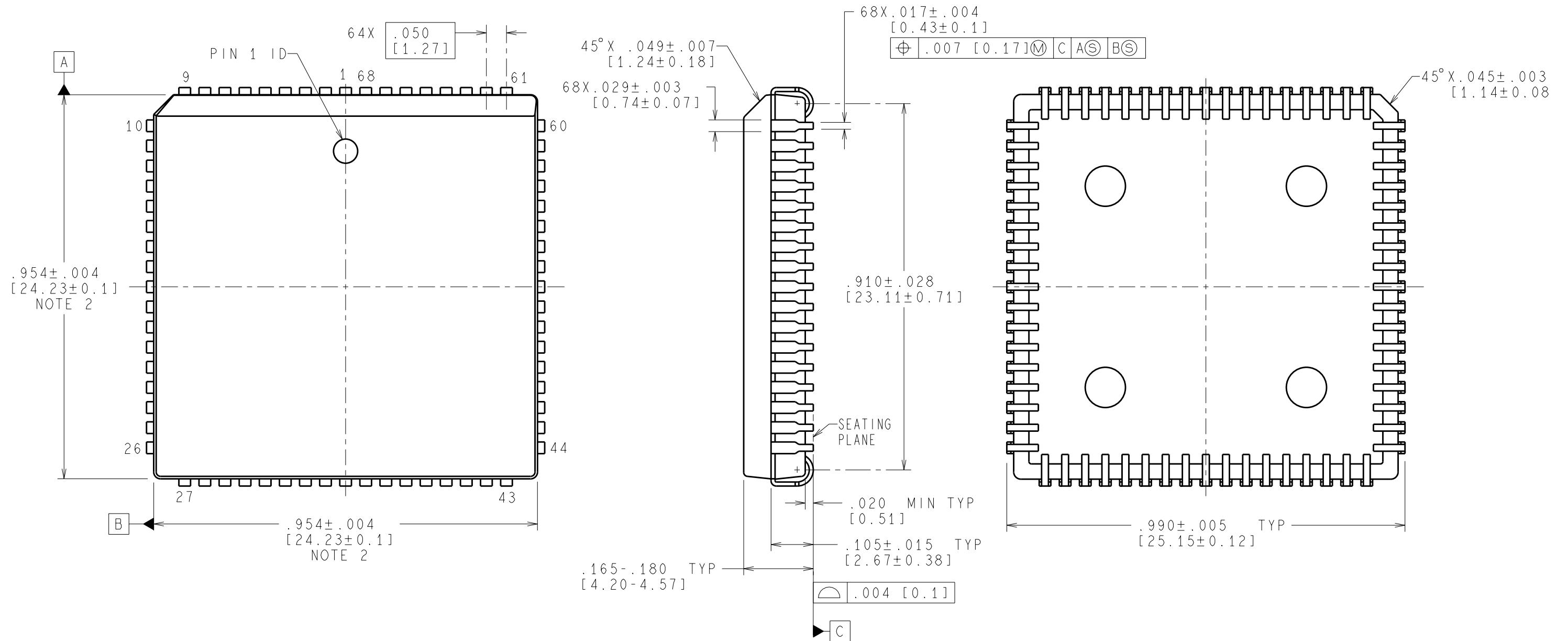


REVISIONS				
REV	DESCRIPTION	E.C.N.	DATE	BY/APP'D
K	REVISE PER CURRENT STANDARDS & JEDEC; UPDATE TITLE; REDRAW IN PROE.	2209	05/08/2007	MS/RW



NOTES: UNLESS OTHERWISE SPECIFIED

- FOR LEAD FINISH THICKNESS AND COMPOSITION, SEE "SOLDER INFORMATION" IN THE PACKAGING SECTION OF THE NATIONAL SEMICONDUCTOR WEB PAGE (www.national.com).
- DIMENSION DOES NOT INCLUDE MOLD PROTRUSION. MAXIMUM ALLOWABLE MOLD PROTRUSION .010in/ 0.25mm PER SIDE.
- REFERENCE JEDEC REGISTRATION MS-018, VARIATION AE.

CONTROLLING DIMENSION IS INCH
VALUES IN [] ARE MILLIMETERS
DIMENSIONS IN () FOR REFERENCE ONLY

APPROVALS	DATE	National Semiconductor		
DRAWN MARTA SUCHY	05/08/2007	2900 Semiconductor Dr., Santa Clara, CA 95052-8090		
DFTG. CHK. THANH LEQUANG	05/08/2007	PLASTIC CHIP CARRIER, J-BEND, .954x.954x.172in, 68 LEAD, .050in PITCH		
ENGR. CHK. RANDALL WALBERG	05/08/2007			
PROJECTION	SCALE	SIZE	DRAWING NUMBER	REV
	NTS	B	(SC)MKT-V68A	K
	FORMERLY: N/A			SHEET 1 of 1